



IT-180

CCL : IT-180TC
Prepreg: IT-180BS

High Tg / Lead Free / High Reliability Laminate & Prepreg

- ANSI Type : **FR-4.0**
- Applicable IPC-4101 /21/24/26/121/124/129 ; IPC-4103 /250/550
- Excellent CAF resistance / Good through-hole reliability / High thermal reliability
- For automotive, Telecommunications, high layer PCB and heavy copper applications

Laminate properties

Items	IPC TM-650	Typical Value	Unit
Peel Strength, minimum			
A. Low profile copper foil(35um)	2.4.8	5	lb/inch
B. Standard profile copper foil(35um)		8	
Volume Resistivity	2.5.17.1	1x10 ⁹	MΩ-cm
Surface Resistivity	2.5.17.1	1x10 ⁸	MΩ
Moisture Absorption, maximum	2.6.2.1	0.12	%
Permittivity (Dk, 50% resin content)			
A. 1GHz	2.5.5.9	4.2	--
B. 2GHz	2.5.5.13	4.2	
C. 5GHz	2.5.5.13	4.1	
D. 10GHz	2.5.5.13	4.0	
Loss Tangent (Df, 50% resin content)			
A. 1GHz	2.5.5.9	0.017	--
B. 2GHz	2.5.5.13	0.018	
C. 5GHz	2.5.5.13	0.019	
D. 10GHz	2.5.5.13	0.020	
Flexural Strength, minimum			
A. Length direction	2.4.4	480-510	N/mm ²
B. Cross direction		410-440	
Young's Modulus			
A. Warp direction	ASTM D3039	18	Gpa
B. Fill direction		17	
Thermal Stress 10 s at 288°C			
A. Unetched	2.4.13.1	Pass	Rating
B. Etched		Pass	
Flammability	UL94	V-0	Rating
Comparative Tracking Index (CTI)	ASTM D3638 / UL 746	CTI 3 (175-249)	Class (Volts)
Maximum Operating Temperature(MOT)	UL 746	130	°C
Glass Transition Temperature(DSC)	2.4.25	175	°C
Decomposition Temperature(5% W.L)	2.4.24.6	350	°C
X/Y Axis CTE (40°C to 125°C)	2.4.41	11-13 / 13-15	ppm/°C
	2.4.24.5	11/12	ppm/°C
Z-Axis CTE			
A. Alpha 1	2.4.24	50	ppm/°C
B. Alpha 2		250	ppm/°C
C. 50 to 260 Degrees C		3.0	%
Thermal Resistance			
A. T260	2.4.24.1	>60	Minutes
B. T288		20	Minutes